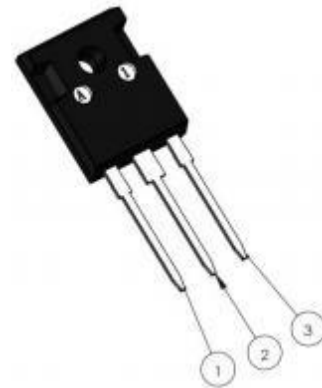


Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

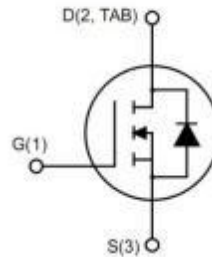
Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Easy to parallel and simple to drive
- ROHS Compliant, Halogen free



Application

- EV Charging
- DC/DC Converters
- Switch Mode Power Supplies
- UPS
- Solar PV inverters



Ordering Information

Part Number	Marking	Package	Packaging
JX3S0040065M	JX3S0040065M	TO247-3	Tube

Absolute Maximum Ratings(Tc=25C)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	650	V
I_D	Drain Current(continuous)at Tc=25C	60	A
I_D	Drain Current(continuous)at Tc=100C	48	A
I_{DM}	Drain Current (pulsed)	132	A
V_{GS}	Gate-Source Voltage	-10/+25	V
P_D	Power Dissipation Tc = 25°C	325	W
T_J, T_{stg}	Junction and Storage Temperature Range	-55 to +150	C

Electrical Characteristics(T_J = 25C unless otherwise specified)
Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu A, V_{GS}=0V$	650			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=650V,$ $V_{GS}=0V, T_J=250C$		5	100	μA
I_{GSS}	Gate-body Leakage Current	$V_{DS}=0V ;$ $V_{GS} = -10 \text{ to } 20V$		10	250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=10mA$	2	3	4	V
$V_{GS(on)}$	Recommended turn-on Voltage	Static		20		V
$V_{GS(off)}$	Recommended turn-off Voltage			-5		V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=20V, I_D=15A$		38	49	mΩ
		$V_{GS}=20V, I_D=15A$ $T_J=150^\circ C$		50		mΩ

Typical Performance-Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input Capacitance	V _{DS} =600V, f=1MHz, V _{AC} =25mV		1866		pF
C _{oss}	Output Capacitance			115		pF
C _{rss}	Reverse Transfer Capacitance			9		pF
g _{fs}	Transconductance	V _{DS} =20V, I _D =20A		13		S
E _{oss}	Coss Stored Energy	V _{DS} =600V, f=1MHz		22		μJ
E _{on}	Turn-On Energy (Body Diode)	V _{DS} =400V, V _{GS} =-5V/20V, I _D =20A, L=100μH T _J =150°C		220		μJ
E _{off}	Turn-Off Energy (Body Diode)			45		μJ
Q _g	Total Gate Charge	V _{DS} =400V, V _{GS} =-5V/20V, I _D =20A		81		nC
Q _{gs}	Gate-source Charge			21		nC
Q _{gd}	Gate-Drain Charge			21		nC
R _{G(int)}	Internal Gate Resistance	f=1MHz, V _{AC} =25mV		3.5		Ω
t _{d(on)}	Turn-on Delay Time	V _{DS} =400V, V _{GS} =-5V/20V, I _D =20A, L=100 μH R _{ext} =2.5Ω		12		ns
t _r	Rise Time			35		ns
t _{d(off)}	Turn-off Delay Time			22		ns
t _f	Fall Time			9		ns

Typical Performance-Reverse Diode(T_J = 25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{FSD}	Forward Voltage	V _{GS} =0V, I _F =7.5A, T _J =25°C		5.2	6	V
		V _{GS} =0V, I _F =7.5A, T _J =150°C		4.8	6	V
I _S	Continuous Diode Forward Current	V _{GS} =0V, T _C =25°C		30.5		A
t _{rr}	Reverse Recovery Time	V _{GS} =-5V, I _F =15A, V _R =400V, T _J =150°C di/dt= 2400 A/μs		36		nS
Q _{rr}	Reverse Recovery Charge			160		nC
I _{rrm}	Peak Reverse Recovery Current			10.5		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.38	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of T_J(max)=150°C

Electrical Characteristics

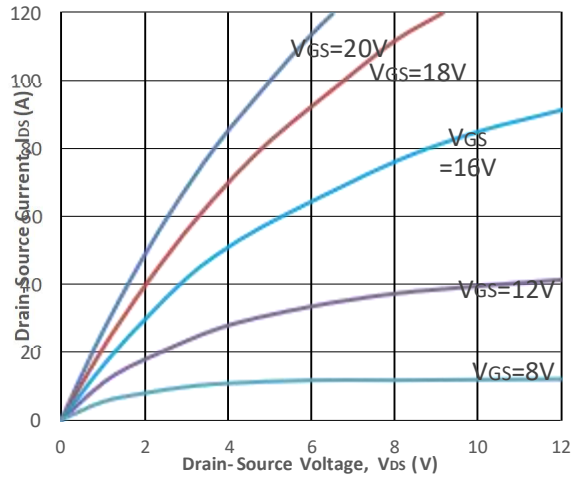
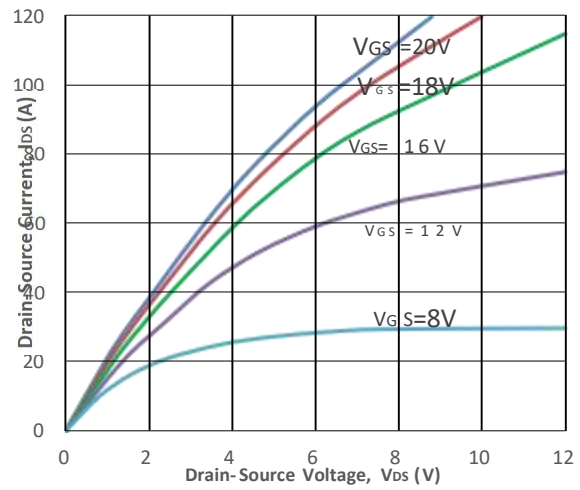
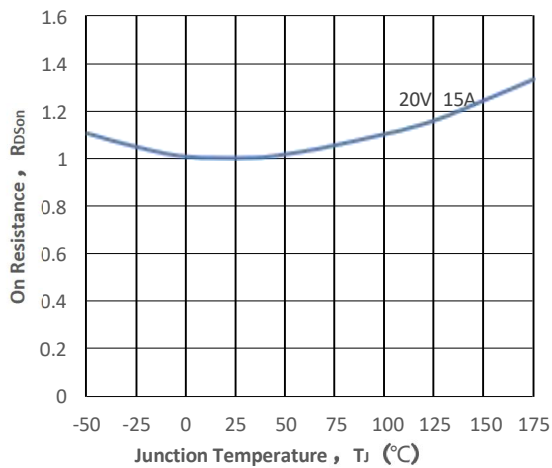
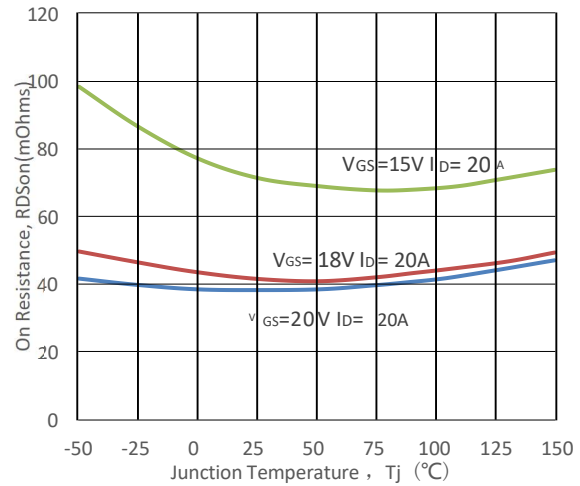
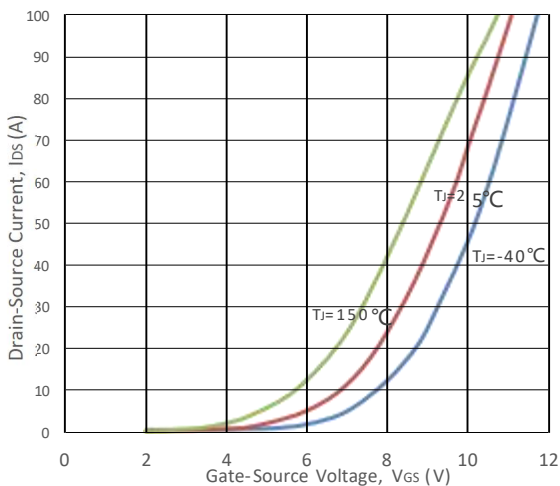
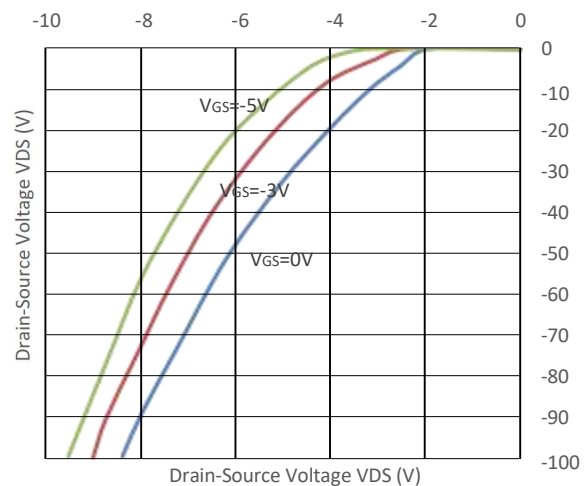
Fig1. Output characteristics ($T_J = 25^\circ\text{C}$)

Fig2. Output characteristics ($T_J = 150^\circ\text{C}$)

Fig3. Normalized On-Resistance vs. Temperature

Fig4. On-Resistance vs. Temperature

Fig5. Transfer Characteristic

Fig6. Body Diode Characteristic at 25°C


Fig7.Threshold Voltage vs. Temperature

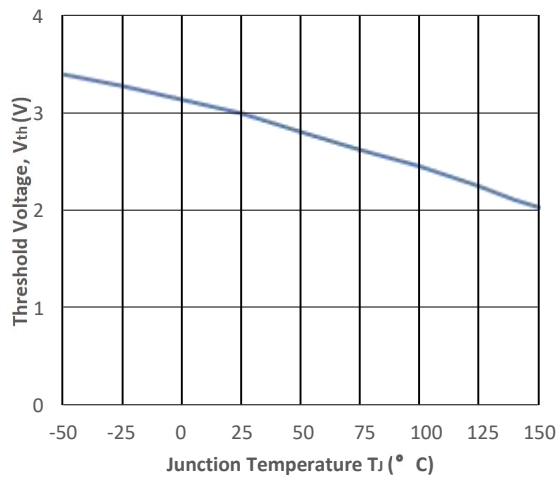


Fig8. Gate Charge Characteristics

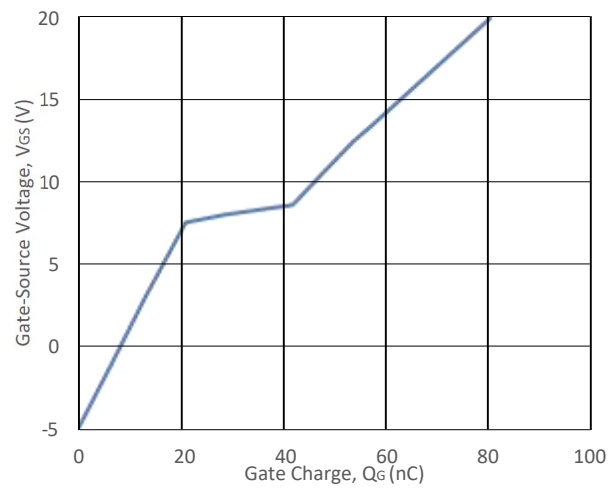


Fig9. 3rd Quadrant Characteristic at 25 $^{\circ}C$

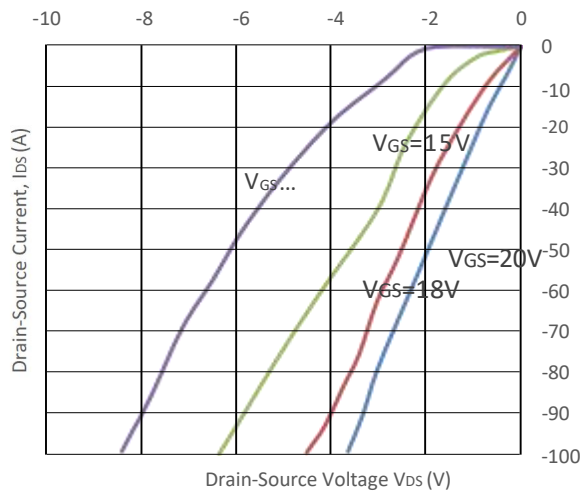


Fig10. Output Capacitor Stored Energy

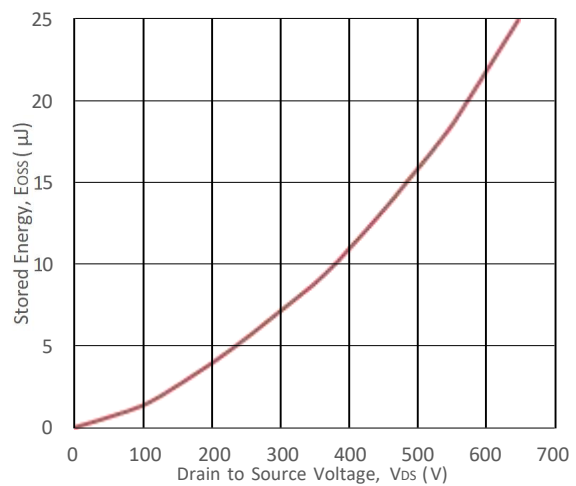


Fig11. Capacitances vs. Drain-Source

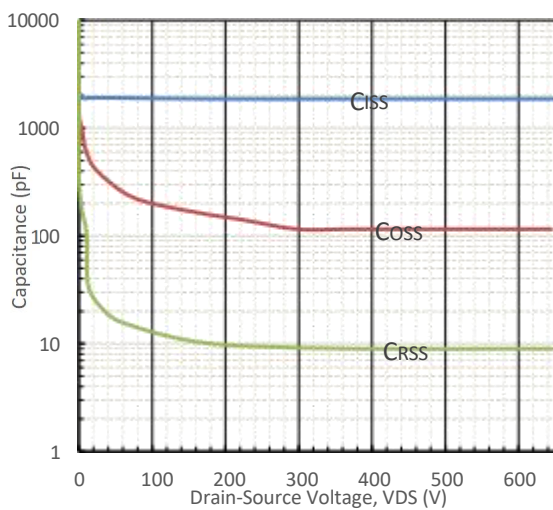


Fig12. Max Power Dissipation Derating Vs T_c

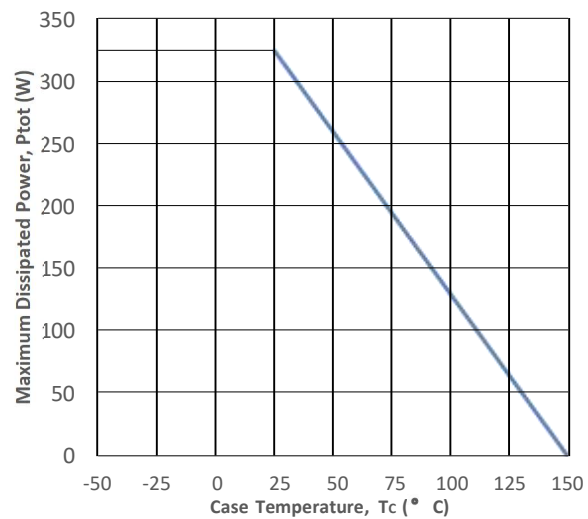
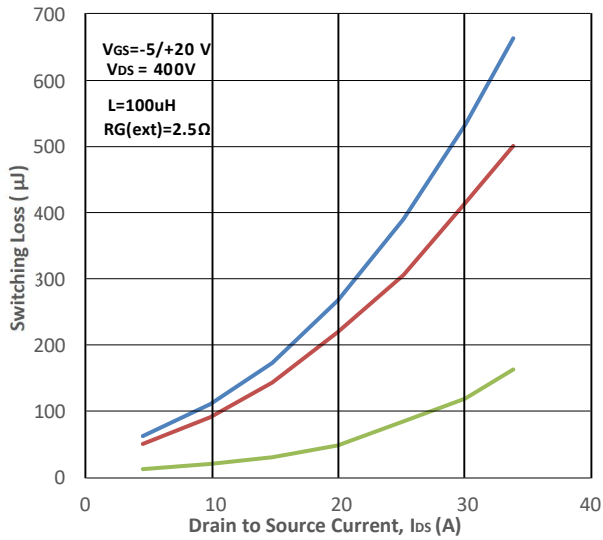
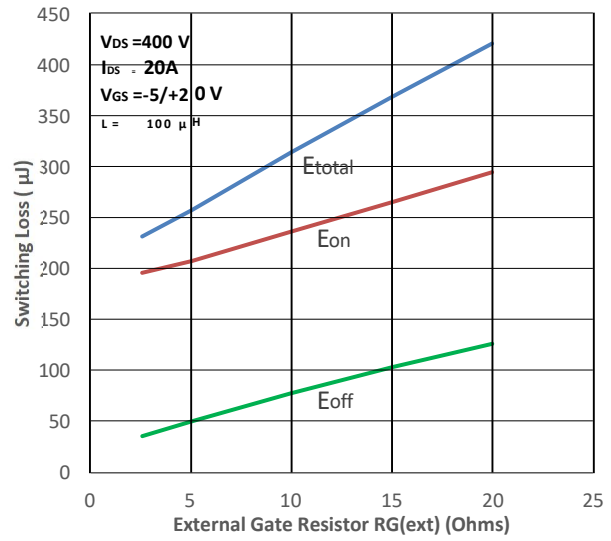
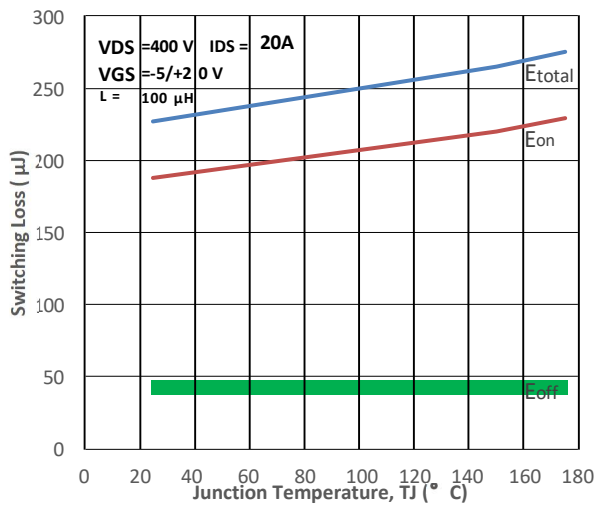
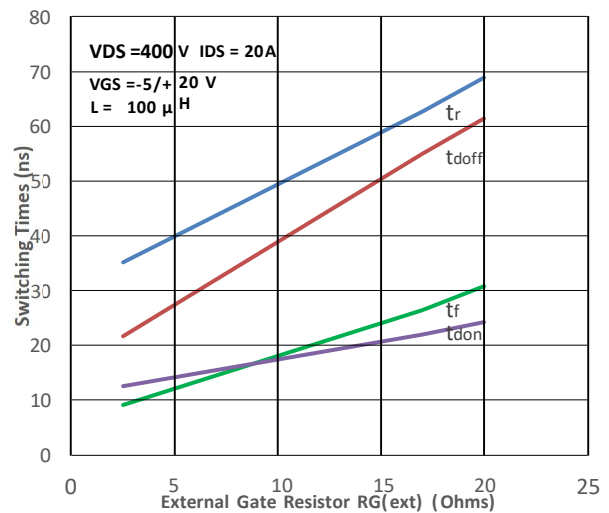
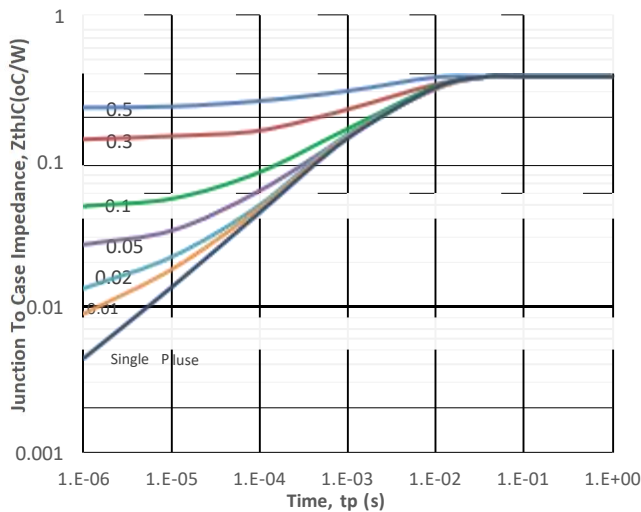
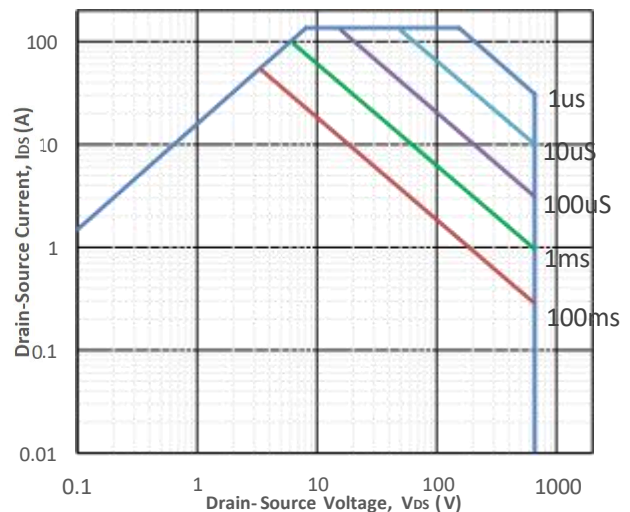
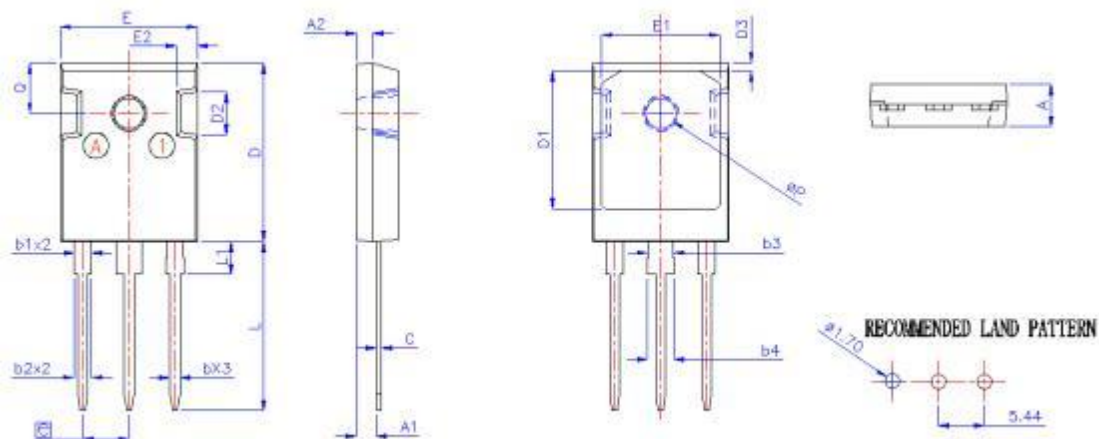


Fig13. Switching Energy vs. Drain Current

Fig14. Switching Energy vs. $R_{G(ext)}$

Fig15. Switching Energy vs. Temperature

Fig16. Switching Times vs. $R_{G(ext)}$

Fig17. Transient Thermal Impedance

Fig18. Safe Operating Area


Package Drawing:

Dimensions (UNIT: mm)

SYMBDLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.90	5.00	5.10	0.193	0.197	0.201
A1	2.31	2.42	2.52	0.091	0.095	0.099
A2	1.90	2.00	2.10	0.075	0.079	0.083
b	1.16	1.22	1.27	0.046	0.048	0.050
b1	1.96	2.02	2.07	0.079	0.080	0.081
b2	2.03	2.07	2.10	0.080	0.0815	0.083
b3	2.96	3.02	3.07	0.117	0.119	0.121
b4	3.03	3.07	3.1	0.119	0.120	0.122
C	0.59	0.62	0.66	0.023	0.024	0.026
D	20.90	21.00	21.10	0.823	0.827	0.831
D1	15.96	16.26	16.56	0.628	0.640	0.652
D2	4.3			4.3		
D3	0.8	0.95	1.1	0.031	0.037	0.043
e	5.44 BSC				0.214 BSC	
E	15.95	16.15	16.35	0.628	0.636	0.644
E1	13.82	14.02	14.26	0.544	0.552	0.561
E2	4.3				0.169	
L	19.72	19.92	20.12	0.776	0.784	0.792
L1	---	---	3.86	---	---	0.152
Q	5.95 BSC			0.234BSC		
ØP	3.55	3.60	3.70	0.140	0.142	0.146